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				Application Number	10/671,016		
TRANSMITTAL				Filing Date	9/25/2003		
		FORM		First Named Inventor	Dupuis, Timothy J.		
,	to be used for all	anronendense often	initial filing\	Group Art Unit	2817		
(to be used for all correspondence after initial filing)				Examiner Name			
Tot	tal Number of Pa	ges in This Submissio	n 4	Attorney Docket Number	SIL.P0061		
			ENCLOSURI	ES (check all that apply)			
	Fee Transmitt	al Form	Assign	ment Papers Application)	After Allowance Communication		
	Fee Attached		Drawing		to Group  Appeal Communication to Board of Appeals and Interferences		
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	After F	inal	Petition		(Appeal Notice, Brief, Reply Brief)  Proprietary Information		
	Affidav	rits/declaration(s)		to Convert a	Status Letter		
	Extension of Time Request		Provisional Application Power of Attorney, Revocation Change of Correspondence Address		Additional Enclosure(s) (please identify below):		
	Express Aband	donment Request	Terminal Disclaimer		- Postcard		
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Response to Missing Parts/ Incomplete Application		Remarks					
		nse to Missing Parts 37 CFR 1.52 or 1.53					
		SIGNAT	URE OF APPI	LICANT, ATTORNEY, OR A	AGENT		
Firm or		Johnson & Asso	iates				
Individual name Bruce A. Johnson		Customer Number 30163					
Signature							
Date		February 12, 200	5)				
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Date

February 12, 2005

Signature

Applicant(s): Dupuis et al.												
Serial No.: 10/671,016												
Filed: 9/25/2003	Group Art Unit: 2817 Examiner:											
Title: STACKED RF POWER AMPLIFIER	Lamine.											
Attorney Docket No.: SIL.P0061												
Commissioner for Patents PO Box 1450												
Alexandria, VA 22313-1450												
INFORMATION DISCLOSURE STATEMENT												
This Information Disclosure Statement is submitted:												
,	(Within three months of filing national application; or date of entry of international application; or before mailing date of first office action on the merits; whichever											
☐ (1) Certification under 37 CFR ☐ (2) a \$180.00 fee under 37 CFR (After the CFR 1.97(b) time per	(1) Certification under 37 CFR 1.97(e), or											
☐ Certification under 37 CFR 1.97 ☐ a \$180.00 fee under 37 CFR 1.1 (Filed after final action or notice	Certification under 37 CFR 1.97(e), and											
□ under 37 CFR 1.97(i) (Not filed under either § 1.97 or	§ 1.98. IDS to be placed in the file)											
Applicant(s) submit herewith Form PTO 1449-Information Disclosure Citation together with copies, of patents, publications or other information of which applicant(s) are aware, which applicant(s) believe(s) may be material to the examination of this application and for which there may be a duty to disclose in accordance with 37 CFR 1.56.												

It is requested that the information disclosed herein be made of record in this application.

Respectfully submitted,

Bruce A. Achnson

Attorney for Applicant(s)

Reg. No. 37361

Date: February 12, 2005

Customer Number 30163

Telephone No.: 512-301-9900

SIGNATION  DOCUMENT NUMBER	APPLICANT FILING DATE  U.S. PATENT DOCI	Dupuis et al. 9 25 2003  UMENTS	CAOL P	2817		SLB CLASS
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